FORM: PTO-1449 (REV: 7-80)	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	Atty Docket No: 98-1191.01	Serial No:	الا
INFORMATION DI	SCLOSURE STATEMENT BY APPLICANT	Applicant: Gurtej S. Sandhu		. 20 2
(37 CFR 1.98(b))	(use several sheets if necessary)	Filing Date: November 9, 2001	Group:	22

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Document				
Number	Date	Name	Class	Subclass
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Initial	,	OTHER ART (including author, title, date, pertinent pages, etc.)
L.J.M.E.	AR	Sabine Penka, et al., Integration Aspects of Flowfill and Spin-on-Glass Process for Sub-0.35µm Interconnects, PROCEEDINGS OF THE IEEE 1998 INTERNATIONAL INTERCONNECT TECHNOLOGY CONFERENCE, at 271-273 (1998).
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